



SUSS MICROTEC INVESTOR PRESENTATION

February 2017

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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I. SUSS MicroTec at a Glance

II. Products & Markets

III. Financials

IV. Outlook

- + Global leader in manufacturing equipment for semiconductor devices
- + SUSS' Equipment creates micro structures that connect micro electronic devices
- + Focus on growth segments: advanced packaging, MEMS, and 2.5D / 3D Integration
- + Attractive end markets: smartphones, tablets, automotive, LED, sensors, IoT, ...

- + Order entry 2016: € 161.1 million
- + Sales 2016: € 177.6 million
- + EBIT 2016: € 11.1 million
- + Net Cash 2016: € 31.1 million
- + Market Cap 01/31/2016: € 145.7 million

- + Q4 order entry above own expectations
- + Record quarterly sales level of € 69.5 million
- + Strong EBIT at € 11.1 million
- + EBIT-margin at 16.0 %
- + Positive free cash flow of € 4.6 million

FY 2016:

- + Key financial figures (order entry, sales and EBIT) within the ambitious guidance
- + Delivery, installation and sales recognition of UV-projection scanners for FOWLP
- + Dr. Franz Richter becomes new CEO of SÜSS MicroTec
- + Refocusing of the sales organization and strategic alliance with Kanematsu in Japan

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 27.6 € million
Sales 28.0 € million
Employees 116

EMEA

Order Entry 48.8 € million
Sales 40.5 € million
Employees 448

ASIA

Order Entry 112.2 € million
Sales 80.0 € million
Employees 134



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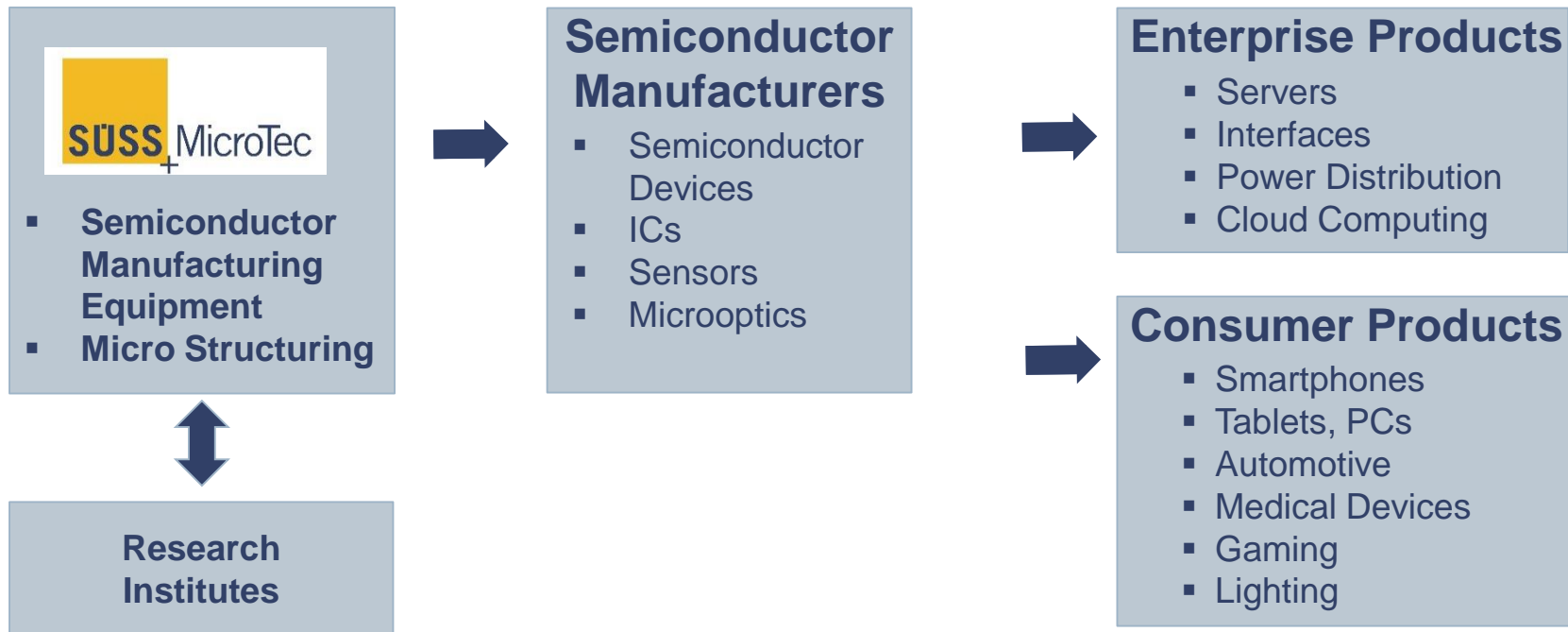


I. SUSS MicroTec at a Glance

II. Products & Markets

III. Financials

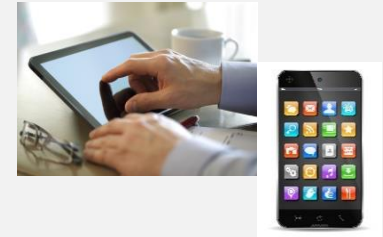
IV. Outlook



- + SUSS MicroTec:**
 - Key player in leading edge semiconductor manufacturing equipment
 - Developer of highly innovative process solutions
- + Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment**

Connectivity & Data Processing

- + Connection through apps, social media, data streaming
- + Connectivity of devices, Internet of Things (IoT)
- + Permanent internet connectivity provided by smartphones and tablet PCs at affordable cost
- + Industry 4.0 connectivity of manufacturing units



Mobility & Automotive

- + Autonomous, electric and plug in hybrid cars, E-Bikes, trains drive the need for power devices and high performance ICs at the same time
- + Growing electronic content and sensors (MEMS) for autonomous cars



Energy Efficiency

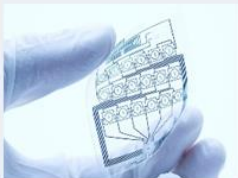
- + Environmental awareness and rising energy costs drive the demand for energy efficient devices
- + Energy efficiency in industrial production
- + Smart energy management in household applications
- + Green energy management systems



Semiconductors

Front End Lithography

- Photomask Cleaning



Advanced Packaging

- Micro-Bumping
- Fan-Out WLP
- Cu Pillar



Chipset Integration

- 3D (TSV) Stacking
- 2.5D Integration



Sensors

MEMS

- Internet of Things
- Automotive
- Mobile Devices
- Industry 4.0
- Biomedical



Lighting

LED

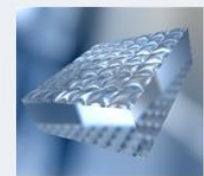
- General Lighting
- HB and UHB



Micro Optics

Advanced Optics

- Wafer Level Optics
- Fiber Optics
- Laser and Lithography Beam Shaping Optics



Micro Optical Components

Micro lens arrays
Diffractive optical elements



Frontend

Mid- and Backend

Photomask Equipment

Photomask Cleaning Equipment



MaskTrackPro

Lithography

Laser Processing Equipment



ELP300

Exposure Systems



Mask Aligner
MA200/300 Gen2



Projection Scanner
DSC300 Gen2

Coaters and Developers



ACS300 Gen2

Bonder

Wafer Bonding Equipment



XBC300 Gen2



XB8

Divisions

Photomask Equipment

Photomask Cleaning
Equipment

9M
2016

Order Entry: 13.3 € million
Sales: 7.1 € million
EBIT: -1.4 € million

Lithography

Laser
Processing
Equipment

Exposure
Systems

Coaters and
Developers

Order Entry: 66.9 € million
Sales: 87.6 € million
EBIT: 7.1 € million

Bonder

Wafer Bonding
Equipment

Order Entry: 12.9 € million
Sales: 6.3 € million
EBIT: -3.2 € million

SUSS MicroTec Group*
9M 2016

Order Entry: 101.5 € million
Sales: 108.1 € million

EBIT: 0.0 € million
EBIT margin: 0%

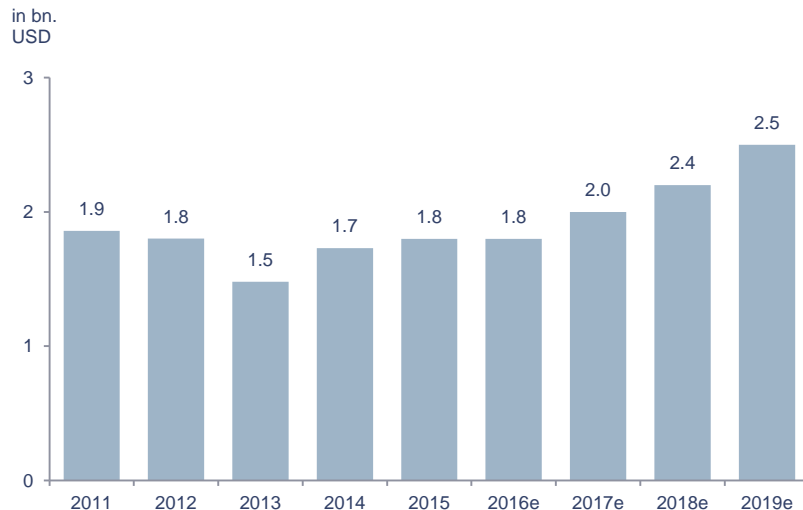
SUSS MicroTec Group*
FY 2016

Order Entry: 161.1 € million
Sales: 177.6 € million

EBIT: 11.1 € million
EBIT margin: 6.3%

* Including Others

Wafer-level packaging (WLP) and assembly equipment



Source: Gartner, January 2017

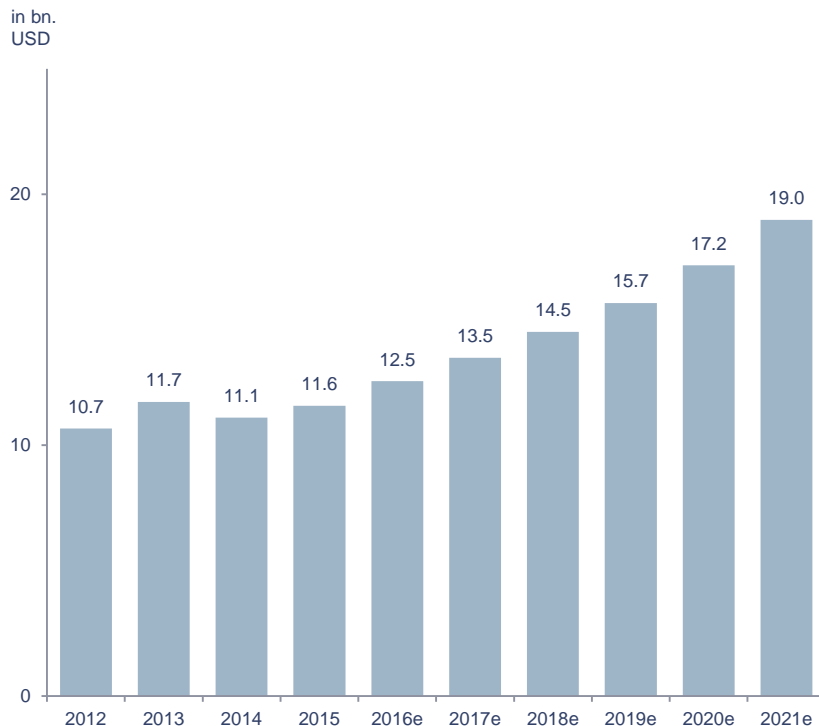
- + Attractive growth opportunities within wafer-level packaging:
 - Fan-out WLP
 - Copper pillar
 - Bumping
- + Grow market share for core products in advanced packaging: coater/developer, UV-projection scanner and mask aligner
- + Timing of new FOWLP production line investments appears to be pushing out
- + Overall semiconductor equipment market is expected to be flat or slightly down yoy in 2016
- + Market forecasts show a return to the growth path in WLP and assembly in 2017

Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (for instance memory and application processors)

FOWLP enables:

- + Smaller form factors**
- + Split die package or multi-die package/SiP**
- + Increased I/O density (Fine line and space (L/S))**
- + Die fabrication from different technology nodes can be assembled in a single package**
- + Excellent electrical and thermal as well as high temperature warpage performance**

MEMS market



Source: Yole 2016

- + Internet of Things (IoT)
- + Smartphones and tablets
- + Automotive applications
- + Health/biomedical applications
- + Grow market share for core products for MEMS: coater/developer, mask aligner, substrate bonder
- + Market re-entry permanent bonder with new differentiated product

2D Packaging

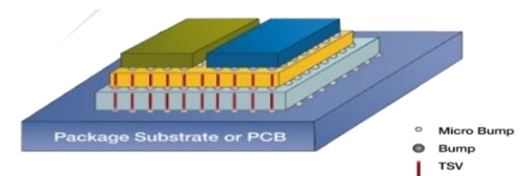
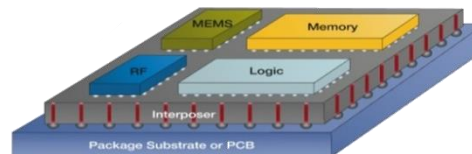
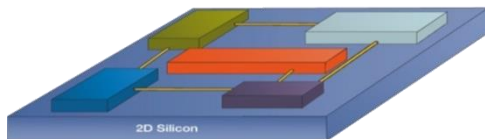
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning drive further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

2.5D Packaging

- Combining of several devices on an interposer addresses the limitations of traditional shrinking while enhancing performance
- Increased packaging density
- Reduced footprint
- Packaging becomes enabler and addresses performance slow down of Moore's Law

3D Integration (TSV)

- Stacking of several devices horizontally enables high performance at a low footprint
- TSV and bonded thin Si technology becomes key enabler for scaling
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 2.5D / 3D integration ("*More than Moore*")

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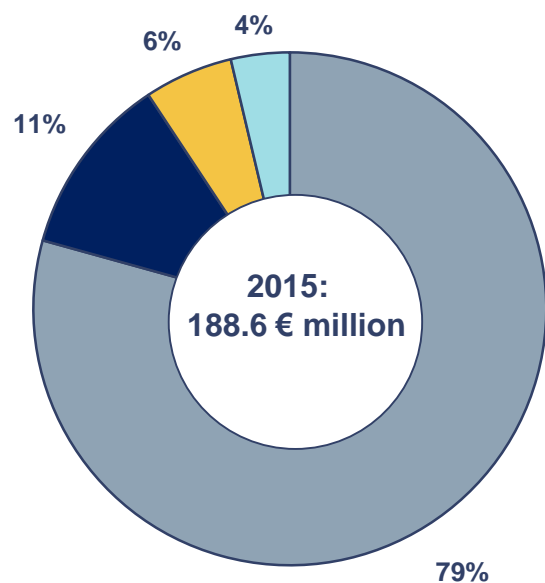
II. Products & Markets

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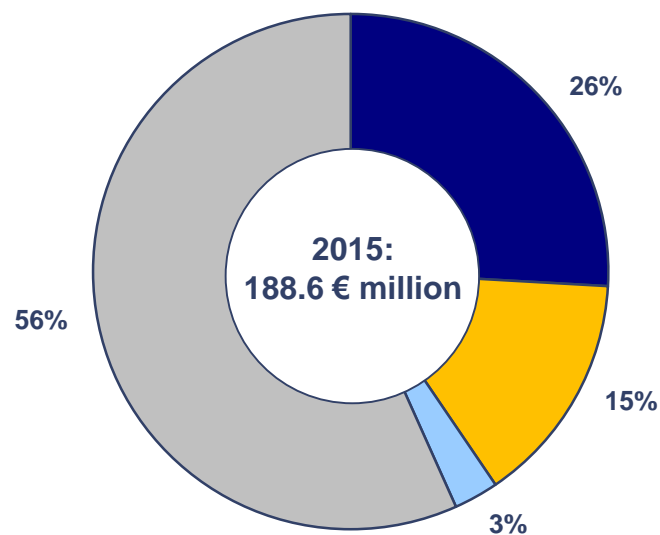
ORDER ENTRY AND SALES BY SEGMENT AND REGION 2015

Order Entry by Segment



- Lithography
- Photomask Equipment
- Substrate Bonder
- Others

Order Entry by Region



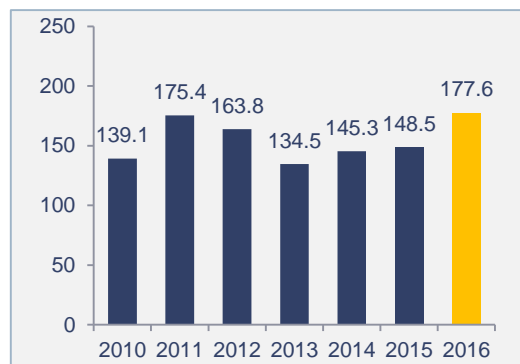
- Europe
- North America
- Japan
- Rest of Asia

LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

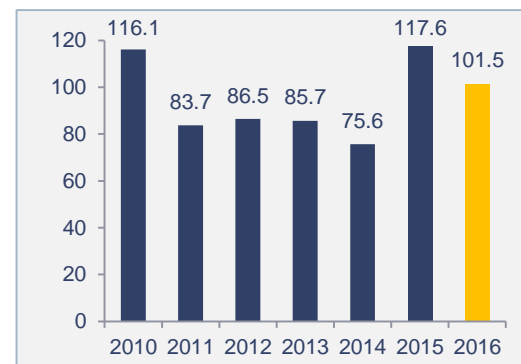
Order Entry in € million



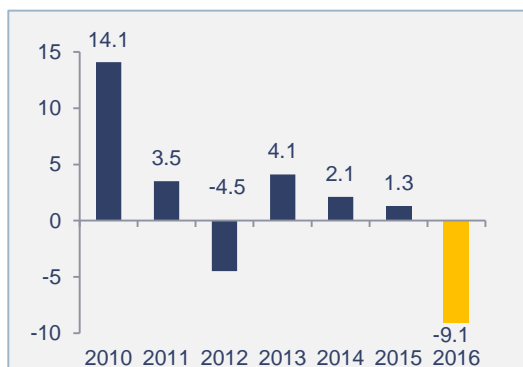
Sales in € million



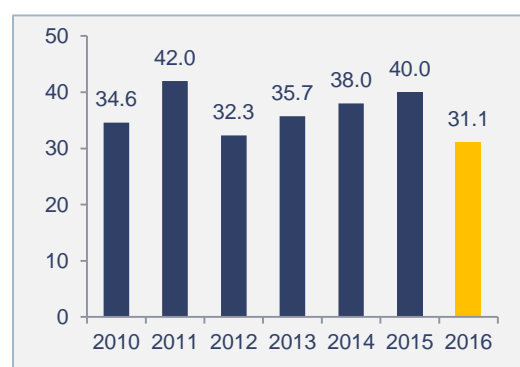
Order Backlog in € million



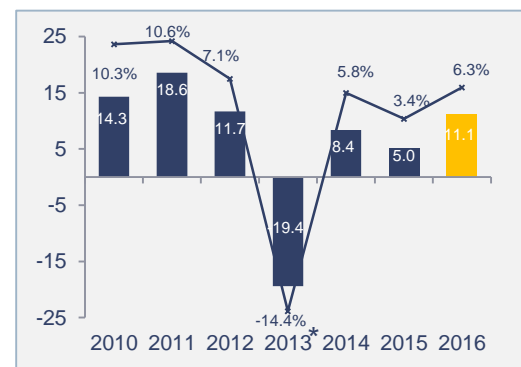
Free Cash Flow in € million



Net Cash in € million



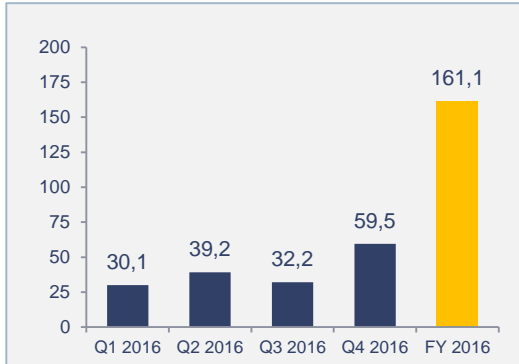
EBIT in € million



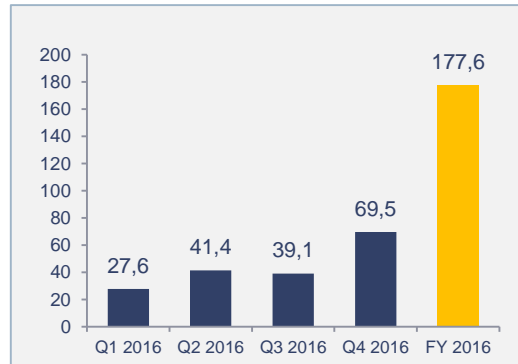
* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

2016 - P&L KEY FIGURES BY QUARTER

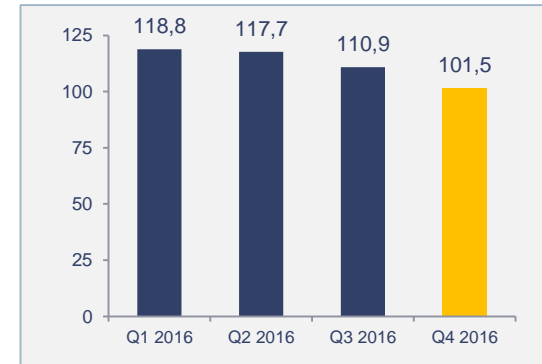
Order Entry in € million



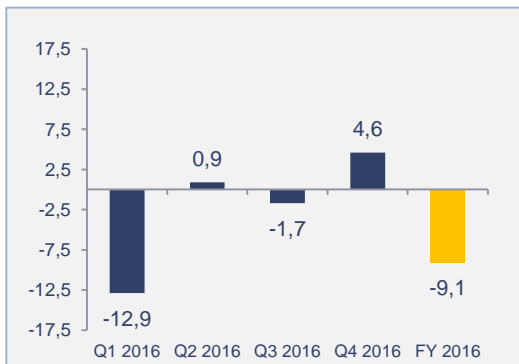
Sales in € million



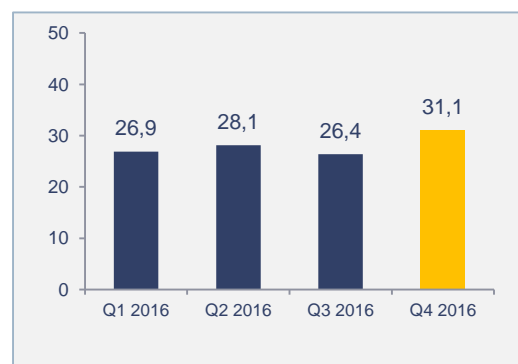
Order Backlog in € million



Free Cash Flow in € million



Net Cash in € million



EBIT in € million

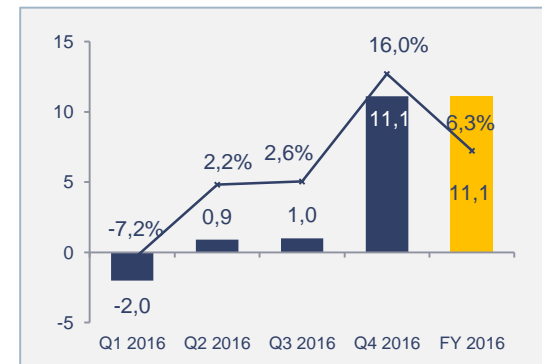


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Short-term

- + Grow market share for core products in all market segments
- + Traction for new advanced lithography products from SUSS MicroTec Photonic Systems
- + Stabilize Company at positive EBIT and cash generation, continue revenue growth:
 - Gross margin 30-35% ✓

Mid-term

- + Focused product portfolio
- + Positive EBIT from Bonder Division and Photonic Systems
- + Successful new adjacent market entries (leverage existing technologies to grow SAM)
- + Continue revenue growth at positive EBIT and cash generation:
 - Sales of >200M
 - Gross margin >35% ✓ (excluding Photonic Systems)
 - EBIT margin >5% ✓

Long-term

- + Continue revenue growth at positive EBIT and cash generation:
 - Sales of >200M
 - Gross margin >35%
 - EBIT margin 10%

Market Outlook

- + Gartner expects the semiconductor market to grow by 7.2% in 2017
- + This would mark a new record level of 364.1 bn \$ (2016: 339.7 bn \$)
- + Market growth will be driven by automotive and industrial applications, the memory segment and the Internet of Things
- + Semi expects the semiconductor equipment market to grow strongly by 9.2% in 2017
- + Wafel-level-packaging and assembly equipment market is expected to grow by 10.7% in 2017 after 3.9% in 2016 (Gartner)
- + Yole expectes MEMS-market CAGR 2015 – 2021 of 13% (unit growth)

SUSS MicroTec Outlook

- + FY 2017: Sales € 160 – 170 million
 EBIT € 9 – 13 million
- + Q1 2017: Order entry € 25 - 35 million



Thank you!

SÜSS MicroTec AG
Schleissheimer Str. 90
85748 Garching

www.SUSS.com

Contact

Franka Schielke

Tel.: +49 89-32007- 161

Fax.: +49 89-32007- 451

Email: franka.schielke@suss.com

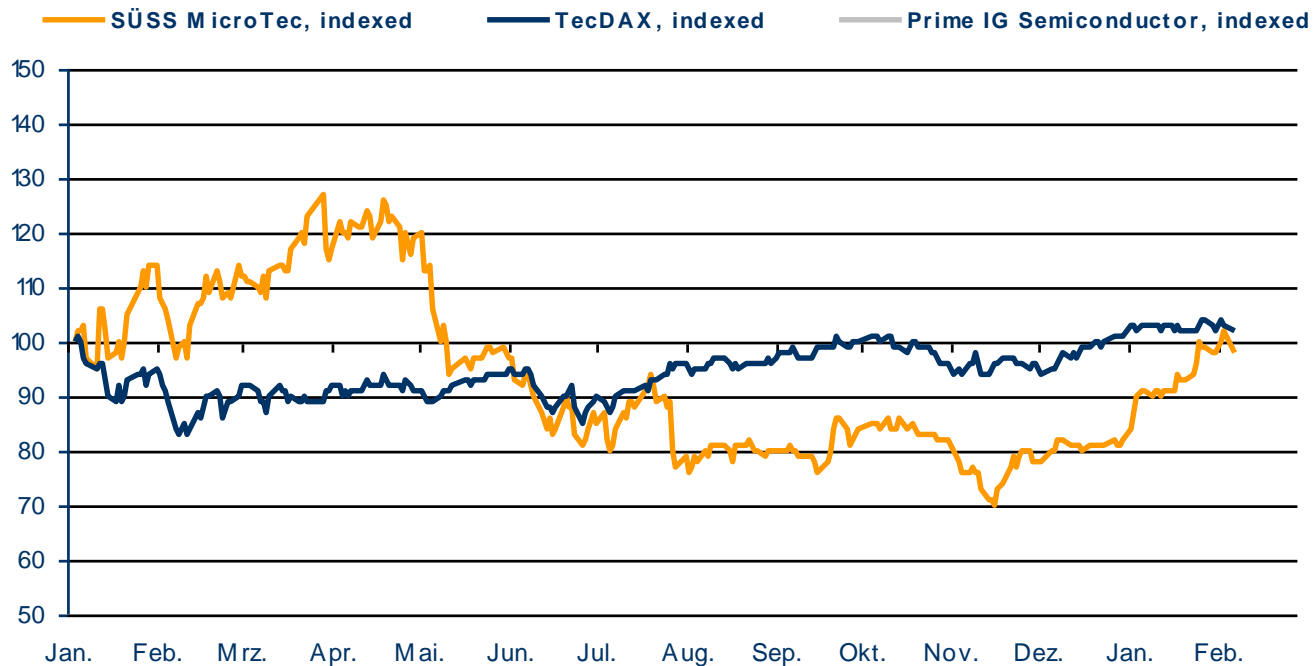
SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching
Germany
www.suss.com

Financial Calendar 2017

Annual Report 2016	30 Mar
Quarterly Report 2017	4 May
Annual General Meeting 2017, Munich	31 May
Interim Report 2017	10 Aug
Nine-month Report 2017	9 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2016: 4.88 €)

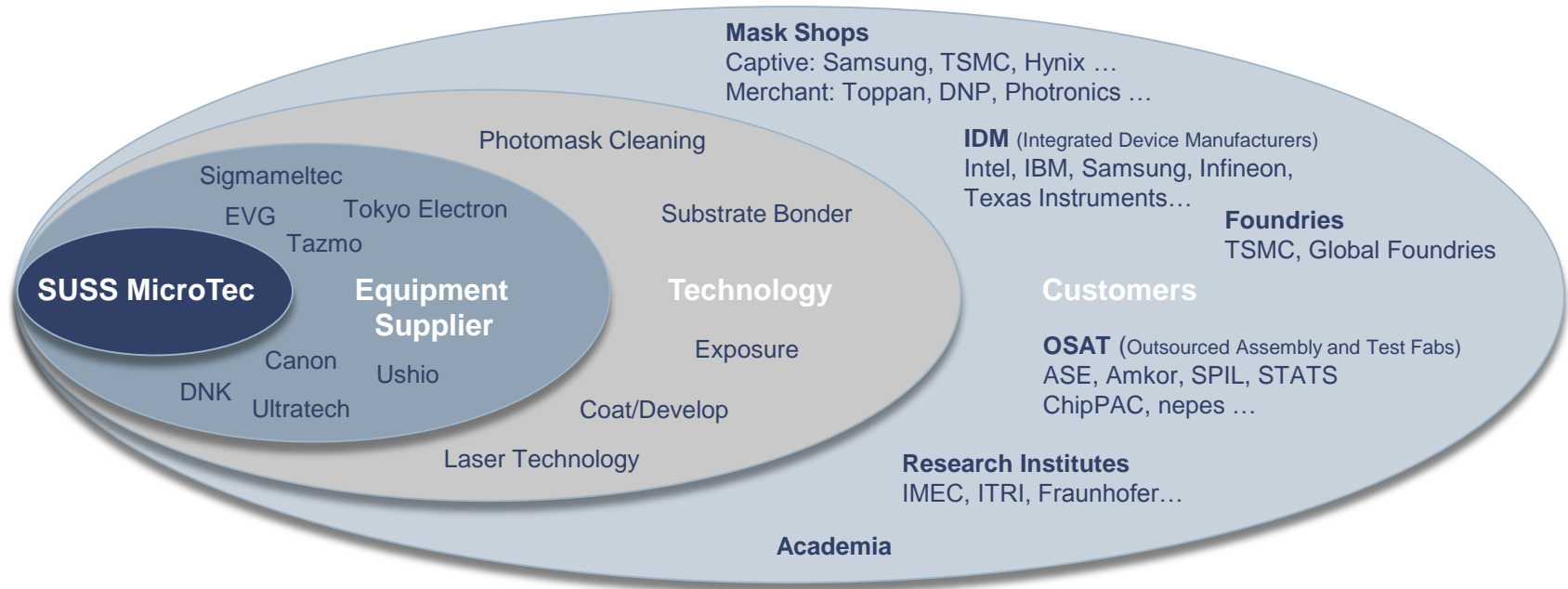


Major Shareholders:

Sycomore	5.2%
Henderson	5.1%
Universal	5.1%
Lupus Alpha	3.2%
Dimensional	3.0%

Average daily trading volume January 2016 – January 2017: ~ 163.000

MAIN COMPETITORS AND PEER GROUP



Peer Group

BE Semiconductor:

equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy

Ultratech:

steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)

Kulicke & Soffa:

design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)

Rudolph Tech:

equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)

EV Group:

equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Production facility ~15,000 m²



Garching*

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Production facility ~9,000 m²



USA

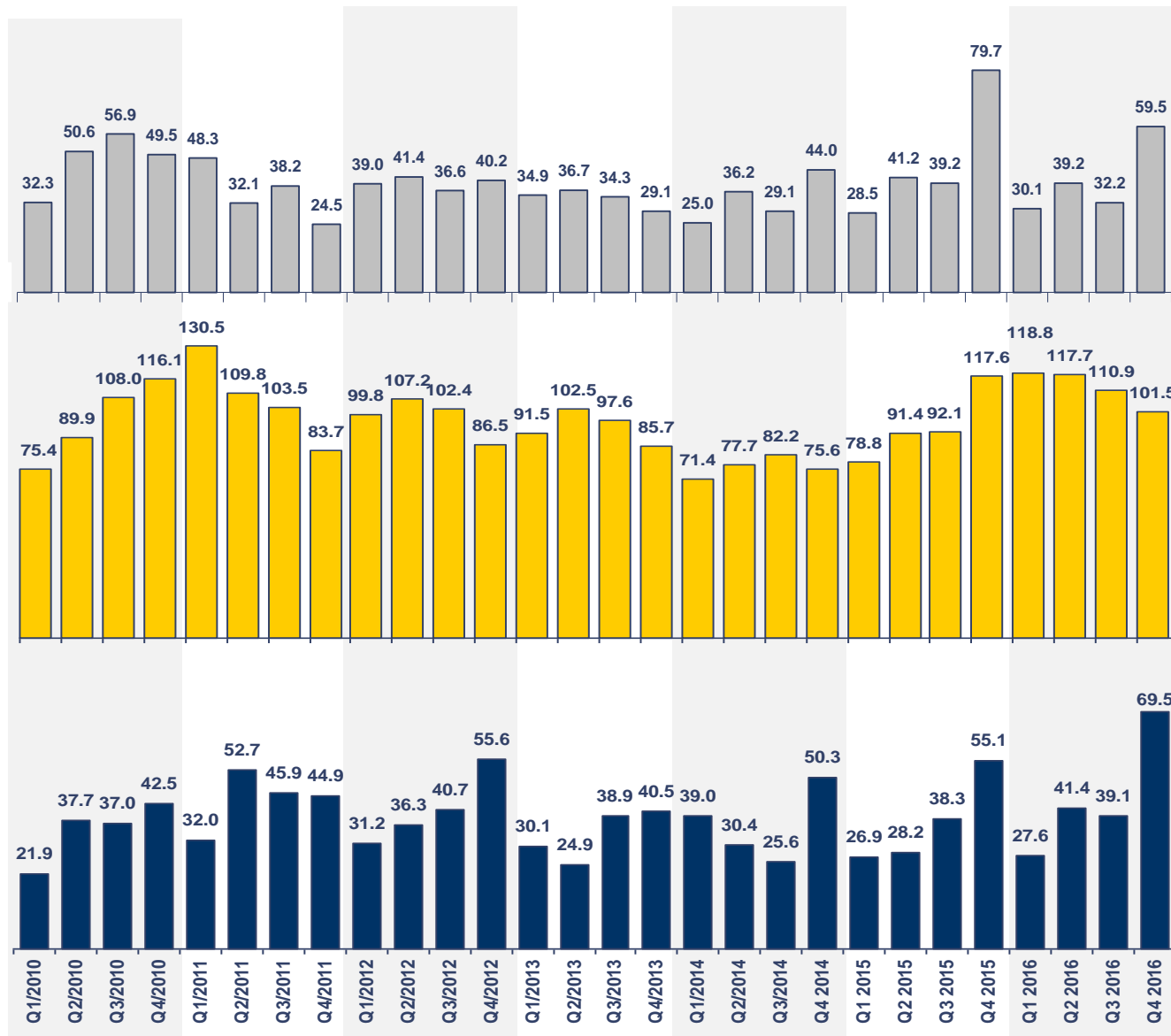
Corona (California)

- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Production facility ~7,000 m²



*Production site is owned by SUSS MicroTec

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

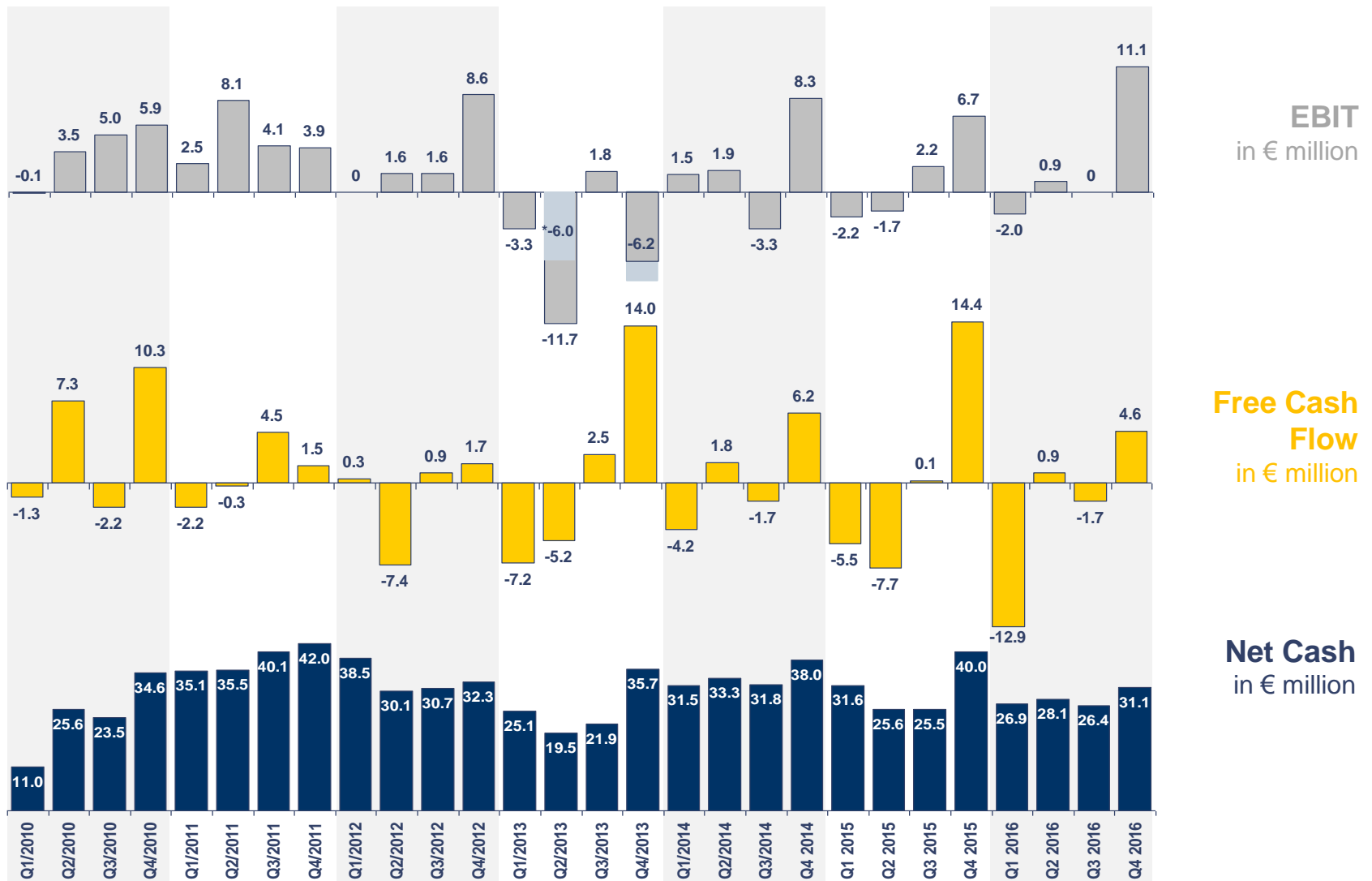


Order Entry
in € million

Order Backlog
in € million

Sales
in € million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

KEY FINANCIALS Q4 2016 AND FULL YEAR 2016

in € million	Q4 2016	Q4 2015	in %
Order Intake	59.5	79.7	-25.3%
Order Backlog 12/31	--	--	--
Revenue	69.5	55.1	26.1%
EBIT	11.1	6.7	65.7%
<i>EBIT in % of Sales</i>	<i>16.0%</i>	<i>12.2%</i>	<i>3.8%pt</i>
Free Cash Flow*	4.6	14.4	-68.0%
Net Cash	--	--	--
Employees 12/31	--	--	--

	2016	2015	in %
	161.1	188.6	-14.6%
	101.5	117.6	-13.7%
	177.6	148.5	19.6%
	11.1	5.0	>100%
	<i>6.3%</i>	<i>3.4%</i>	<i>2.9%pt</i>
	-9.1	1.3	--
	31.1	40.0	-22.3%
	711	698	1.9%

* before consideration of purchased interest-bearing securities